

### Features

- Fast response time
- Wide temperature range
- High surge current rating
- Low capacitance and insertion loss
- Stable performance throughout life
- Small surface mount package
- RoHS compliant\*

### Applications

- Set top boxes
- Industrial communications
- HVAC controls
- xDSL, POTS, G.Fast
- Antennae

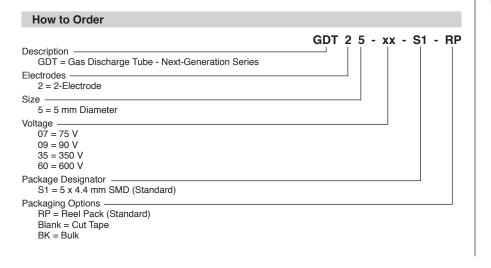
### GDT25 Series - Next-Generation 2-Electrode Gas Discharge Tube Arrestor

#### **General Information**

Bourns' new and improved next-generation surface mount 2-electrode GDT surge protection devices have been designed using Bourns' proprietary, advanced computer simulation techniques and offer industry-leading maximum impulse voltage limiting specifications in a small, environmentally rugged surface mount package. The performance delivered in the Bourns® GDT25 Series helps to significantly heighten protection against induced voltage transients such as lightning and AC induction. Plus, the enhanced level of protection with tighter voltage limiting provided during fast-rising events will reduce stress on downstream components compared to current GDT designs in the same application.

#### **Product Characteristics**

Storage Temperature Range	
Operating Temperature Range	
Climate Category (IEC 60068-1)	
Moisture Sensitivity Level (MSL)	1
ESD Classification - HBM	



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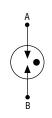
\*RoHS Directive 2015/863, Mar 31, 2015 and Annex.

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### Agency Recognition

Agency	Category	Agency File No.
<b>SN</b> °UL	497B - 4th Edition	<u>E153537</u>

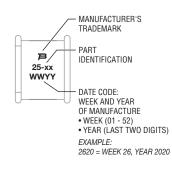
### Circuit Diagram



Note: Gas discharge tubes are bidirectional and non-polarized.

#### **Typical Part Marking**

Represents total content. Layout may vary.



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#### **Electrical Characteristics**

Test Methods per ITU-T K.12, IEEE C62.31 and IEC 61643-311 GDT standards.

	Device Specifications (1)									
Bourns Part No.	DC Sparkover Voltage ±20 % (2) (3) (4)			Insulation Resistance (IR) (6)	Glow Voltage	Arc Voltage	Glow to Arc Transition Current	Capacitance	DC Holdover Voltage (8)	
	100 V/s	100 V/µs	1 kV/µs	(7)	10 mA	> 1 A		1 MHz	< 150 ms	
GDT25-07	75 V	350 V	600 V	> 2 GΩ ~ 70 V						50.14
GDT25-09	90 V	350 V	500 V		70.1/	5.1		.0.0	52 V	
GDT25-35	350 V	650 V	800 V		~ 70 V	~ 5 V	<1A	< 0.6 pF		
GDT25-60	600 V	1000 V	1100 V					135 V		

			Life Ra	tings <sup>(9)</sup>		
Bourns Part No.	Max. Surge Current	Nominal Impulse Discharge Current			Nomin Discharge	
	8/20 µs	8/20 μs	10/350 <i>µ</i> s	10/1000 µs	11 Cycles @ 60 Hz	1 Second
GDT25-07	10 kA 1 Operation	7 kA 10 Operations		100 A 300 Operations	20 Arms 1 Operation	7 Arms 10 Operations
GDT25-09					25 Arms 1 Operation	
GDT25-35					20 Arms 1 Operation	
GDT25-60					25 Arms 1 Operation	

#### Notes:

- (1) At delivery AQL 0.65 Level II, DIN ISO 285.
- (2) DC and Impulse Sparkover values are in ionized mode @ 25 °C.
  (3) Bourns recommends reflowing surface mount devices per *IPC/*
- JEDEC J-STD-020 rev. D.
- <sup>(4)</sup> Surface mount GDTs may exhibit a temporary increase in the DC Sparkover Voltage after the solder reflow process. The DC Sparkover Voltage will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary increase in DC Sparkover Voltage.
- (5) Impulse Sparkover voltage is expressed as a maximum value, with a 99 % probability of measured values within limit.
- <sup>(6)</sup> IR limits after Life Ratings > 100 M $\Omega$ .
- (7) IR Test Voltage: 50 V for GDT25-07 and GDT25-09, 100 V for GDT25-35 and GDT25-60.
- (8) Network applied (per ITU-T K.12 Edition 9.0, Section 7).
- (9) DC Sparkover Voltage limits after Life Ratings may exceed +20 % but will continue to protect without venting (per *ITU-T K.12 Edition 9.0, Section 6*, where applicable).

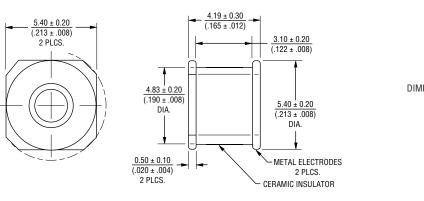
Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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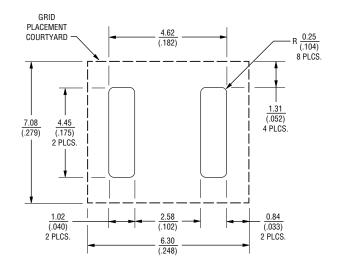
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#### **Product Dimensions**



MM DIMENSIONS: (INCHES)

#### **Recommended Pad Layout**



MM DIMENSIONS: (INCHES)

Note: Recommended PCB land pattern in compliance with IPC-7351.

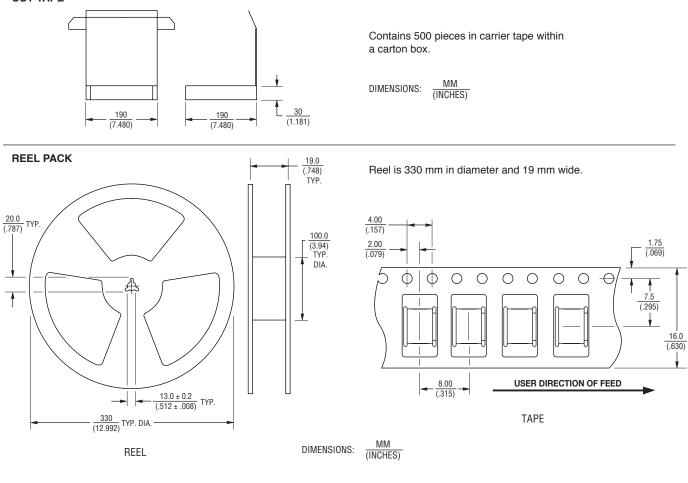
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### **Packaging Specifications**

Model	Standard Packaging Quantity					
Model	Bulk (Bag) Box Reel		Reel	Cut Tape		
GDT25				500		
GDT25-BK	250	1000				
GDT25-RP			1500			

#### **CUT TAPE**

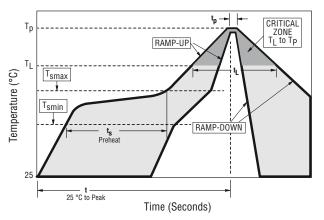


± 0.3 TOLERANCES (EXCEPT WHERE NOTED): X.X (± .012) X.XX  $\frac{\pm 0.15}{(\pm .006)}$ DEGREES ±1°

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### Soldering Parameters - Reflow Soldering



#### Notes:

Bourns recommends reflowing surface mount devices per *IPC/JEDEC J-STD-020 rev D.* 

Surface mounted components (SMD) may exhibit a temporary increase in the DC Sparkover Voltage after the solder reflow process. The components should recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC Sparkover Voltage.

Soldering Parameters - Hand Soldering	

Reflow C	ondition	Pb-free Assembly
	Temperature Min. (T <sub>S(min)</sub> )	150 °C
Preheat	Temperature Max. (T <sub>S(max)</sub> )	200 °C
	Time (Min. to Max.) (T <sub>S</sub> )	60 - 120 seconds
	Ramp-up Rate Temperature (T <sub>L</sub> ) to Peak)	3 °C / second max.
T <sub>S(max)</sub> to	o T <sub>L</sub> - Ramp-up Rate	5 °C / second max.
Reflow	Temperature (T <sub>L</sub> ) (Liquidus)	217 °C
Reliow	Temperature (T <sub>L</sub> )	60 - 150 seconds
Peak Tem	nperature (T <sub>p</sub> )	260 +0/-5 °C
Time with Temperat	in 5 °C of Actual Peak ure (T <sub>p</sub> )	10 – 30 seconds
Ramp-do	wn rate	6 °C / second max.
Time from 25 °C to Peak Temperature $(T_p)$		8 minutes max.
Do not Ex	ceed	260 ° C

Solder Iron Temperature	350 °C ± 5 °C
Heating Time	5 seconds max.